

Resonant Mode Combi IGBT®

The Thunderbolt IGBT® used in this Resonant Mode Combi is a new generation of high voltage power IGBTs. Using Non- Punch Through Technology, the Thunderbolt IGBT® offers superior ruggedness and ultrafast switching speed.

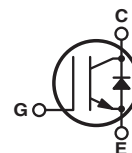
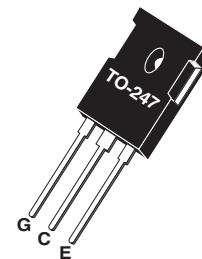
Features

- Low Conduction Loss
- Low Gate Charge
- Ultrafast Tail Current shutoff
- Low forward Diode Voltage (V_F)
- Ultrasoft Recovery Diode

- SSOA Rated
- RoHS Compliant 

Typical Applications

- Induction Heating
- Welding
- Medical
- High Power Telecom
- Resonant Mode Phase Shifted Bridge



MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	APT30GT60BRDL(G)	UNIT
V_{CES}	Collector-Emitter Voltage	600	Volts
V_{GE}	Gate-Emitter Voltage	± 30	
I_{C1}	Continuous Collector Current @ $T_C = 25^\circ\text{C}$	64	Amps
I_{C2}	Continuous Collector Current @ $T_C = 110^\circ\text{C}$	30	
I_{CM}	Pulsed Collector Current ^①	110	
SSOA	Switching Safe Operating Area @ $T_J = 150^\circ\text{C}$	110A @ 600V	
P_D	Total Power Dissipation	250	Watts
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to 150	$^\circ\text{C}$
T_L	Max. Lead Temp. for Soldering: 0.063" from Case for 10 Sec.	300	

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	Units
$V_{(BR)CES}$	Collector-Emitter Breakdown Voltage ($V_{GE} = 0V, I_C = 250\mu A$)	600			Volts
$V_{GE(TH)}$	Gate Threshold Voltage ($V_{CE} = V_{GE}, I_C = 700\mu A, T_J = 25^\circ\text{C}$)	3	4	5	
$V_{CE(ON)}$	Collector-Emitter On Voltage ($V_{GE} = 15V, I_C = 30A, T_J = 25^\circ\text{C}$)	1.6	2.0	2.5	
	Collector-Emitter On Voltage ($V_{GE} = 15V, I_C = 30A, T_J = 125^\circ\text{C}$)		2.8		
I_{CES}	Collector Cut-off Current ($V_{CE} = 600V, V_{GE} = 0V, T_J = 25^\circ\text{C}$) ^②			50	μA
	Collector Cut-off Current ($V_{CE} = 600V, V_{GE} = 0V, T_J = 125^\circ\text{C}$) ^②			1250	
I_{GES}	Gate-Emitter Leakage Current ($V_{GE} = \pm 20V$)			± 100	nA



CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

DYNAMIC CHARACTERISTICS

APT30GT60BRDL(G)

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C_{ies}	Input Capacitance	Capacitance $V_{GE} = 0V, V_{CE} = 25V$ $f = 1 \text{ MHz}$		1600		pF
C_{oes}	Output Capacitance			155		
C_{res}	Reverse Transfer Capacitance			90		
V_{GEP}	Gate-to-Emitter Plateau Voltage	Gate Charge $V_{GE} = 15V$ $V_{CE} = 300V$ $I_C = 30A$		7.5		V
Q_g	Total Gate Charge ^③			145		nC
Q_{ge}	Gate-Emitter Charge			10		
Q_{gc}	Gate-Collector ("Miller") Charge			60		
SSOA	Switching Safe Operating Area	$T_J = 150^\circ C, R_G = 10\Omega, V_{GE} = 15V, L = 100\mu H, V_{CE} = 600V$	110			A
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (25°C) $V_{CC} = 400V$ $V_{GE} = 15V$ $I_C = 30A$ $R_G = 10\Omega$ $T_J = +25^\circ C$		12		ns
t_r	Current Rise Time			20		
$t_{d(off)}$	Turn-off Delay Time			225		
t_f	Current Fall Time			80		
E_{on1}	Turn-on Switching Energy ^④			525		μJ
E_{on2}	Turn-on Switching Energy (Diode) ^⑤			605		
E_{off}	Turn-off Switching Energy ^⑥			600		
$t_{d(on)}$	Turn-on Delay Time	Inductive Switching (125°C) $V_{CC} = 400V$ $V_{GE} = 15V$ $I_C = 30A$ $R_G = 10\Omega$ $T_J = +125^\circ C$		12		ns
t_r	Current Rise Time			20		
$t_{d(off)}$	Turn-off Delay Time			245		
t_f	Current Fall Time			100		
E_{on1}	Turn-on Switching Energy ^④			570		μJ
E_{on2}	Turn-on Switching Energy (Diode) ^⑤			965		
E_{off}	Turn-off Switching Energy ^⑥			830		

THERMAL AND MECHANICAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction to Case (IGBT)			.50	$^\circ C/W$
$R_{\theta JC}$	Junction to Case (DIODE)			1.0	
W_T	Package Weight		5.9		gm

① Repetitive Rating: Pulse width limited by maximum junction temperature.

② For Combi devices, I_{ces} includes both IGBT and FRED leakages

③ See MIL-STD-750 Method 3471.

④ E_{on1} is the clamped inductive turn-on energy of the IGBT only, without the effect of a commutating diode reverse recovery current adding to the IGBT turn-on loss. Tested in inductive switching test circuit shown in figure 21, but with a Silicon Carbide diode.

⑤ E_{on2} is the clamped inductive turn-on energy that includes a commutating diode reverse recovery current in the IGBT turn-on switching loss. (See Figures 21, 22.)

⑥ E_{off} is the clamped inductive turn-off energy measured in accordance with JEDEC standard JESD24-1. (See Figures 21, 23.)

Microsemi Reserves the right to change, without notice, the specifications and information contained herein.

TYPICAL PERFORMANCE CURVES

APT30GT60BRDL(G)

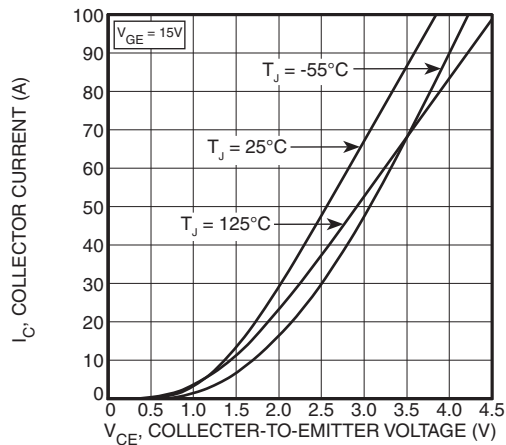


FIGURE 1, Output Characteristics($T_J = 25^\circ\text{C}$)

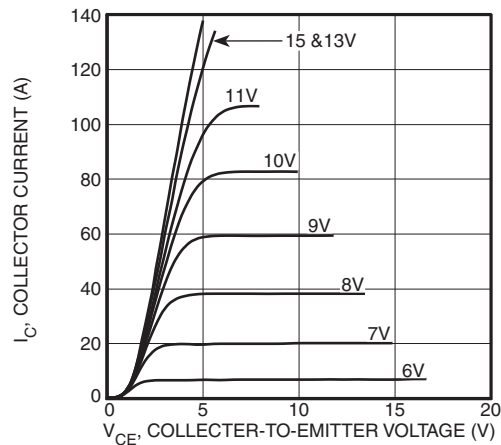


FIGURE 2, Output Characteristics ($T_J = 125^\circ\text{C}$)

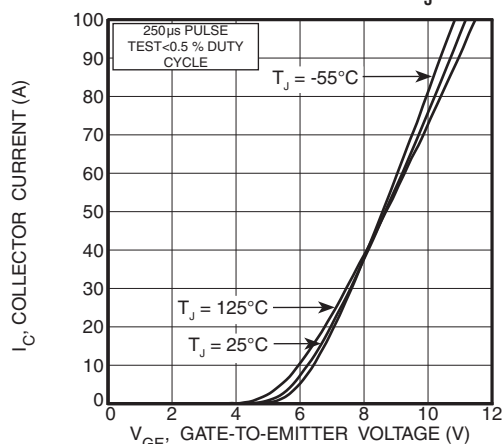


FIGURE 3, Transfer Characteristics

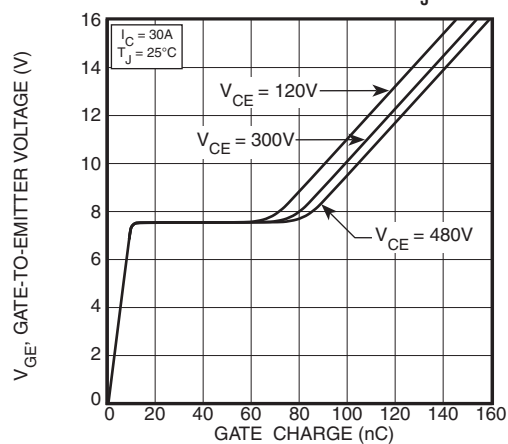


FIGURE 4, Gate Charge

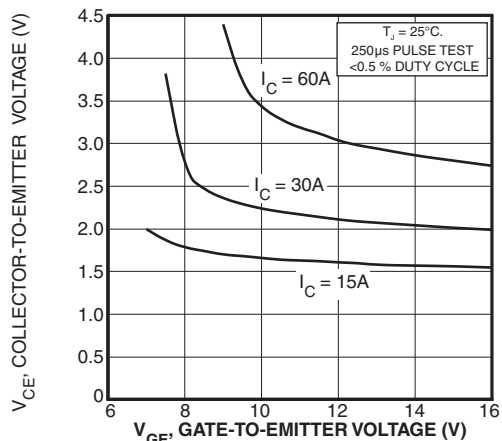


FIGURE 5, On State Voltage vs Gate-to-Emitter Voltage

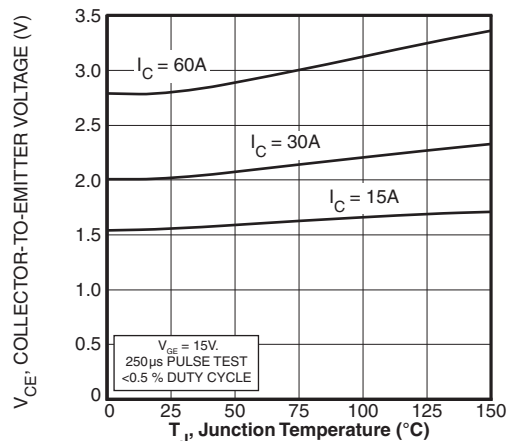


FIGURE 6, On State Voltage vs Junction Temperature

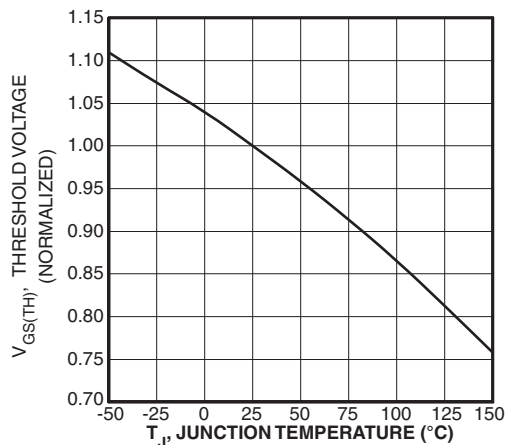


FIGURE 7, Threshold Voltage vs. Junction Temperature

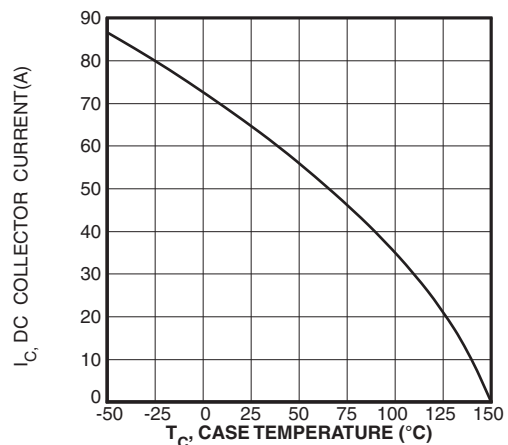


FIGURE 8, DC Collector Current vs Case Temperature

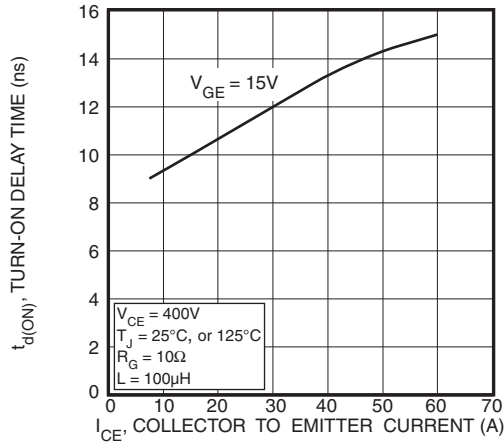


FIGURE 9, Turn-On Delay Time vs Collector Current

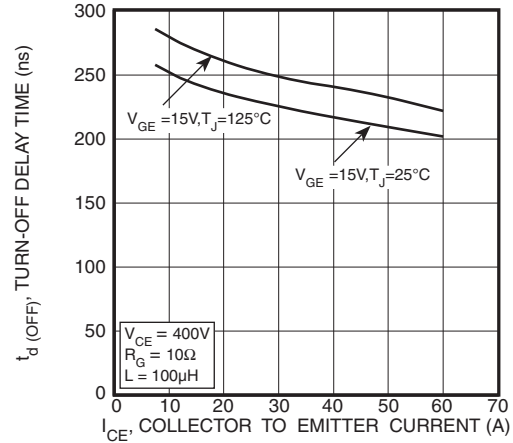


FIGURE 10, Turn-Off Delay Time vs Collector Current

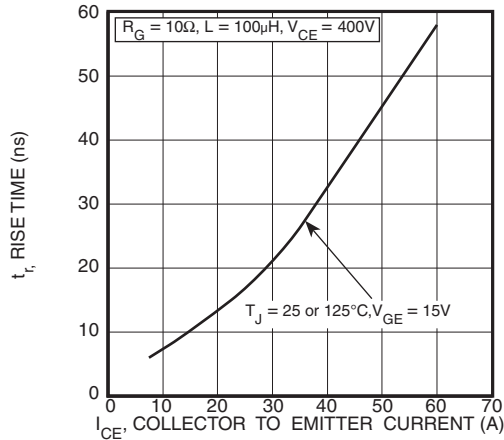


FIGURE 11, Current Rise Time vs Collector Current

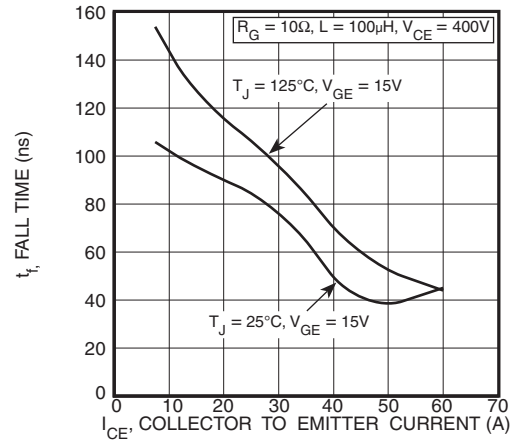


FIGURE 12, Current Fall Time vs Collector Current

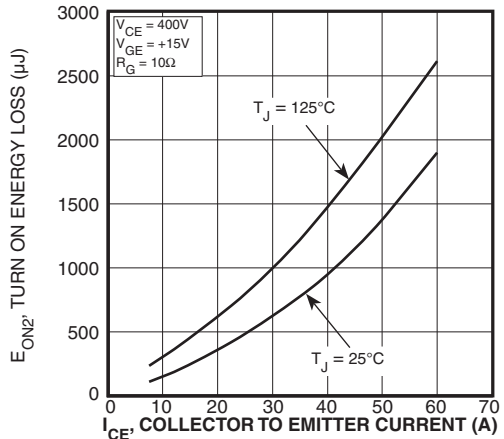


FIGURE 13, Turn-On Energy Loss vs Collector Current

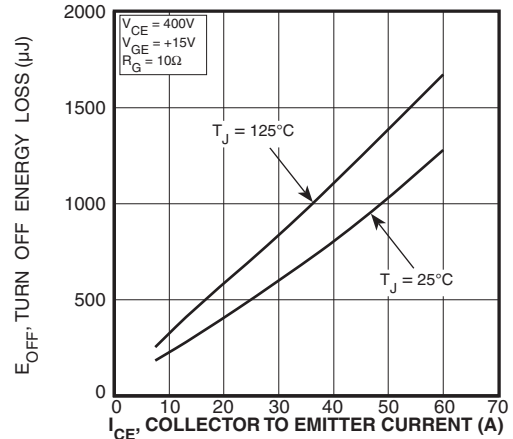


FIGURE 14, Turn Off Energy Loss vs Collector Current

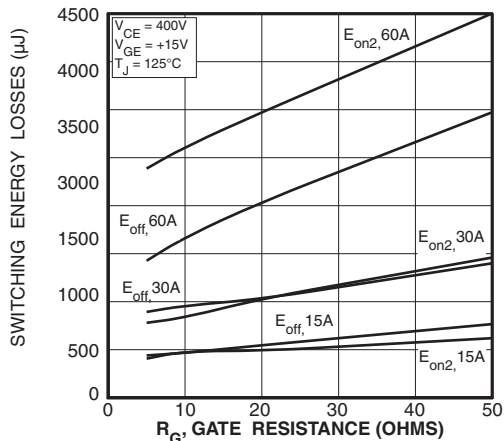


FIGURE 15, Switching Energy Losses vs. Gate Resistance

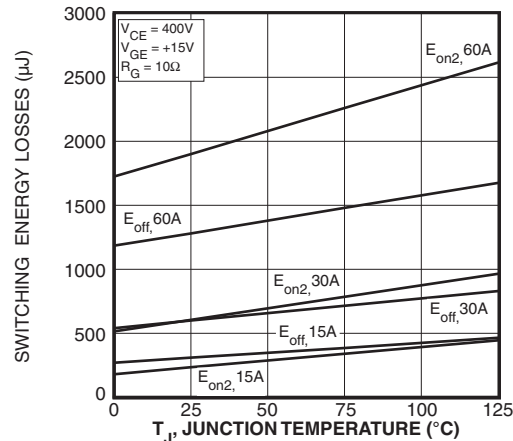


FIGURE 16, Switching Energy Losses vs Junction Temperature

TYPICAL PERFORMANCE CURVES

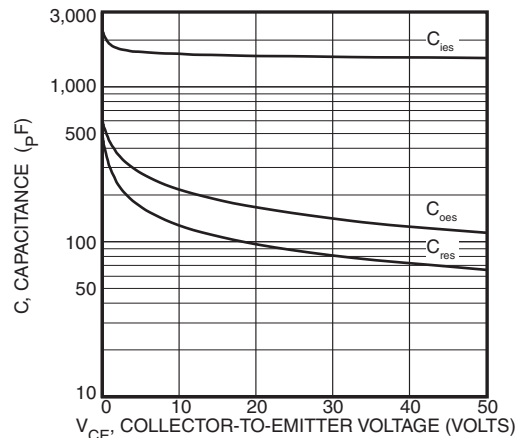


Figure 17, Capacitance vs Collector-To-Emitter Voltage

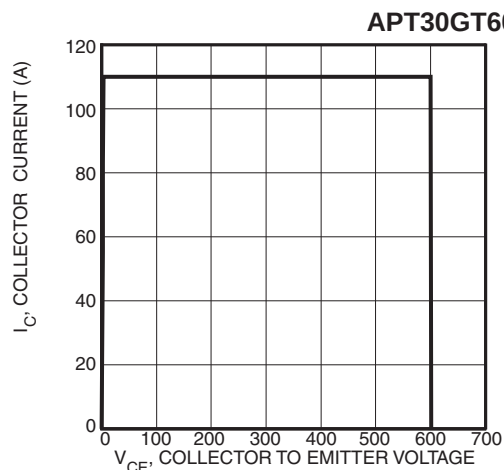


Figure 18, Minimum Switching Safe Operating Area

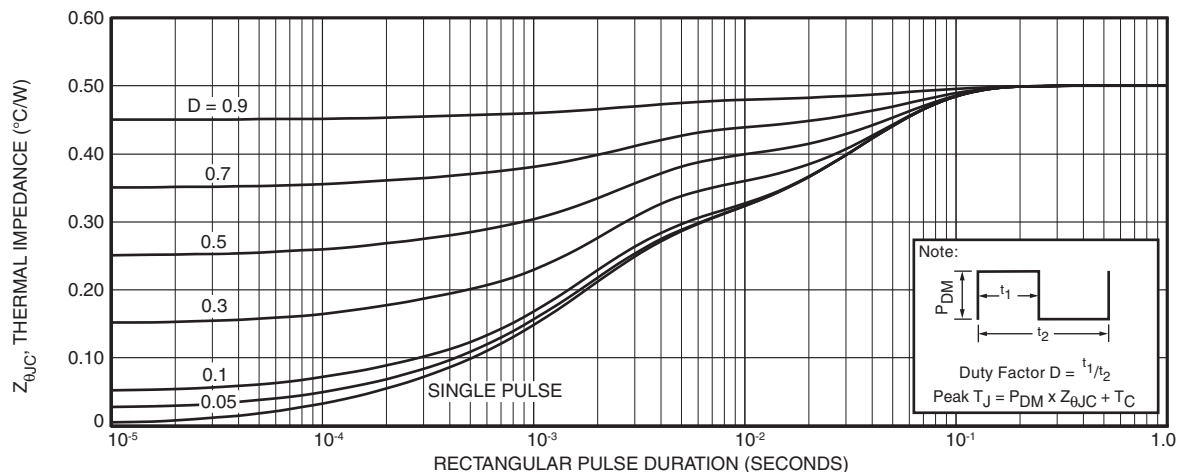


Figure 19a, Maximum Effective Transient Thermal Impedance, Junction-To-Case vs Pulse Duration

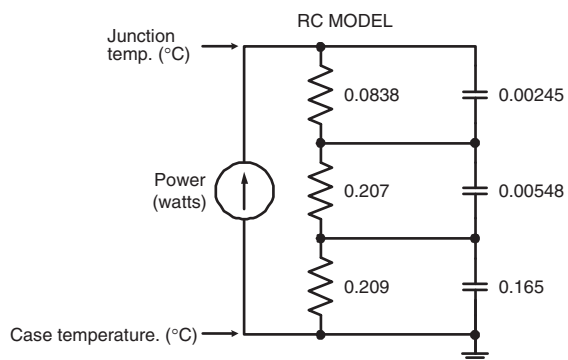


FIGURE 19b, TRANSIENT THERMAL IMPEDANCE MODEL

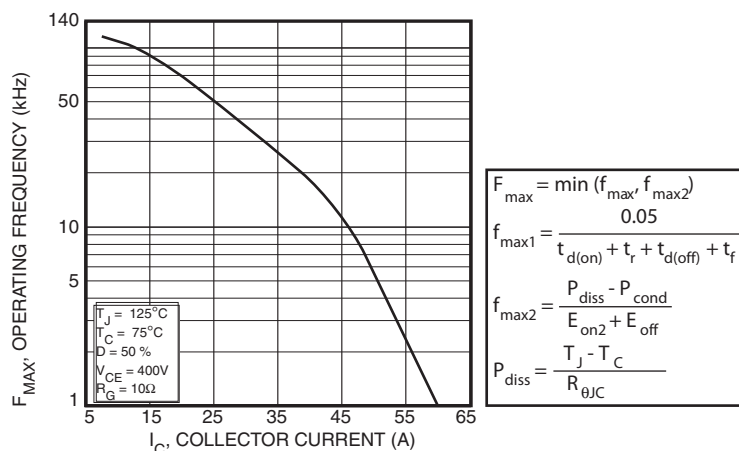
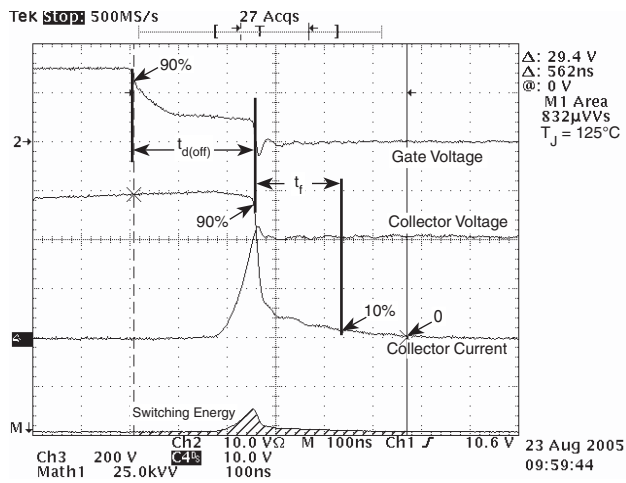
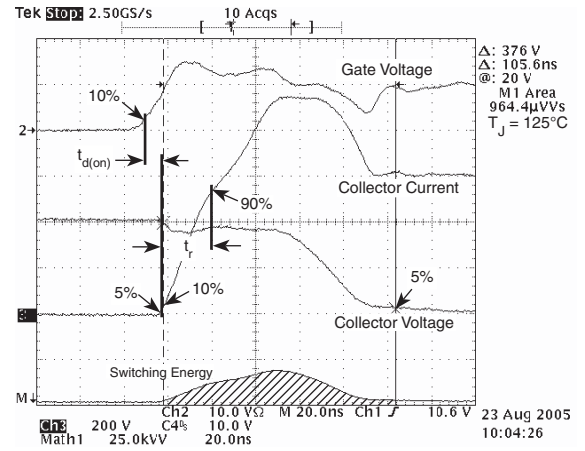
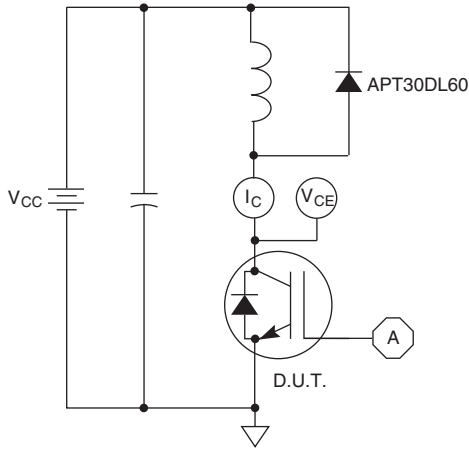


Figure 20, Operating Frequency vs Collector Current



ULTRAFAST SOFT RECOVERY ANTI-PARALLEL DIODE

MAXIMUM RATINGS

All Ratings: $T_C = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Characteristic / Test Conditions	APT30GT60BRDL(G)			UNIT
$I_{F(AV)}$	Maximum Average Forward Current ($T_C = 100^\circ\text{C}$, Duty Cycle = 0.5)		30		Amps
$I_{F(RMS)}$	RMS Forward Current (Square wave, 50% duty)		51		
I_{FSM}	Non-Repetitive Forward Surge Current ($T_J = 45^\circ\text{C}$, 8.3ms)		320		

STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
V_F	Forward Voltage		$I_F = 30\text{A}$	1.25	Volts
			$I_F = 60\text{A}$	2.0	
			$I_F = 30\text{A}, T_J = 125^\circ\text{C}$	1.25	

DYNAMIC CHARACTERISTICS

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
t_{rr}	Reverse Recovery Time	$I_F = 1\text{A}, di_F/dt = -100\text{A}/\mu\text{s}, V_R = 30\text{V}, T_J = 25^\circ\text{C}$	-	64		ns
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}, di_F/dt = -200\text{A}/\mu\text{s}, V_R = 400\text{V}, T_C = 25^\circ\text{C}$	-	317		
Q_{rr}	Reverse Recovery Charge		-	962		nC
I_{RRM}	Maximum Reverse Recovery Current		-	7	-	Amps
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}, di_F/dt = -200\text{A}/\mu\text{s}, V_R = 400\text{V}, T_C = 125^\circ\text{C}$	-	561		ns
Q_{rr}	Reverse Recovery Charge		-	2244		nC
I_{RRM}	Maximum Reverse Recovery Current		-	9	-	Amps
t_{rr}	Reverse Recovery Time	$I_F = 30\text{A}, di_F/dt = -1000\text{A}/\mu\text{s}, V_R = 400\text{V}, T_C = 125^\circ\text{C}$	-	264		ns
Q_{rr}	Reverse Recovery Charge		-	3191		nC
I_{RRM}	Maximum Reverse Recovery Current		-	26		Amps

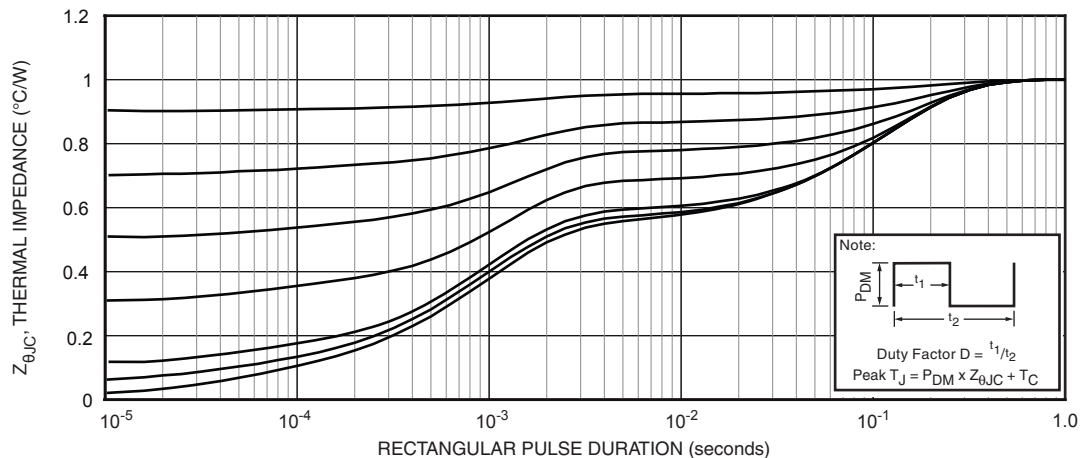


FIGURE 1a. MAXIMUM EFFECTIVE TRANSIENT THERMAL IMPEDANCE, JUNCTION-TO-CASE vs. PULSE DURATION

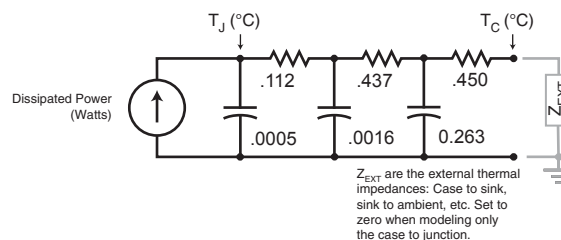


FIGURE 1b. TRANSIENT THERMAL IMPEDANCE MODEL

TYPICAL PERFORMANCE CURVES

APT30GT60BRDL(G)

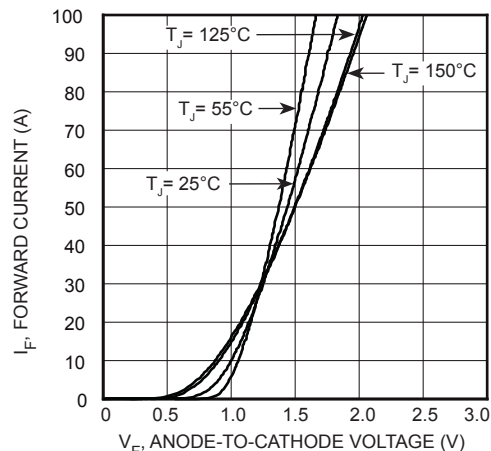


FIGURE 2, Forward Current vs. Forward Voltage

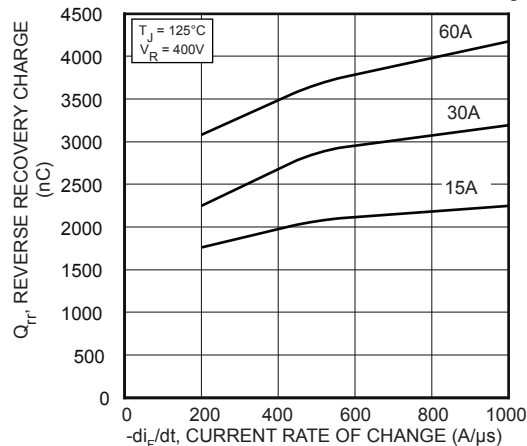


FIGURE 4, Reverse Recovery Charge vs. Current Rate of Change

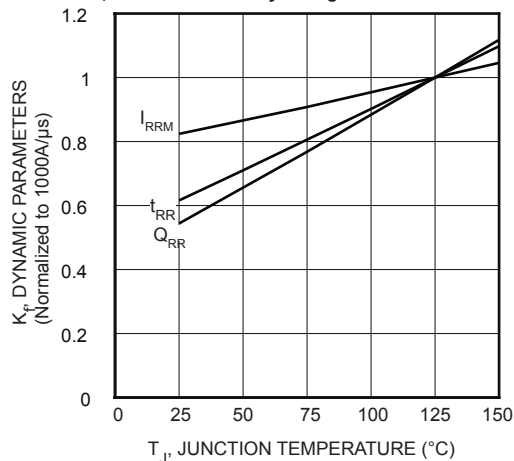


FIGURE 6, Dynamic Parameters vs. Junction Temperature

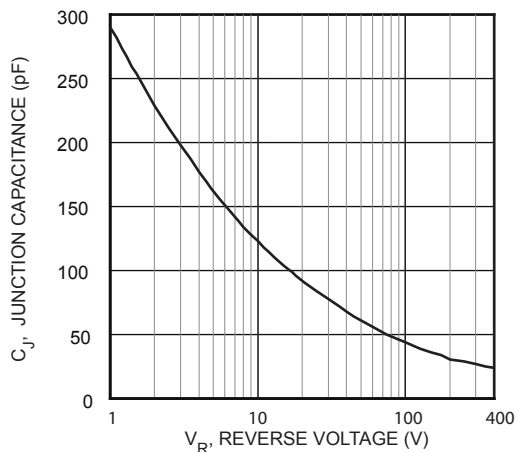


FIGURE 8, Junction Capacitance vs. Reverse Voltage

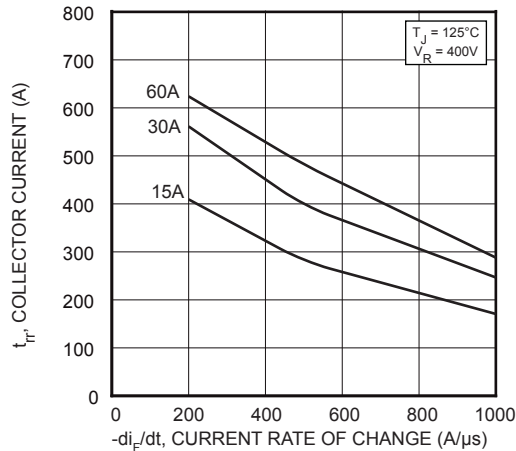


FIGURE 3, Reverse Recovery Time vs. Current Rate of Change

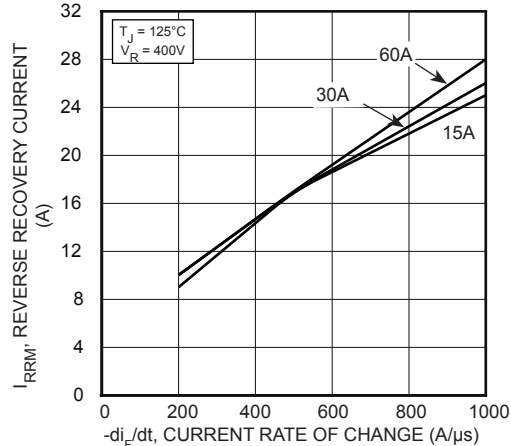


FIGURE 5, Reverse Recovery Current vs. Current Rate of Change

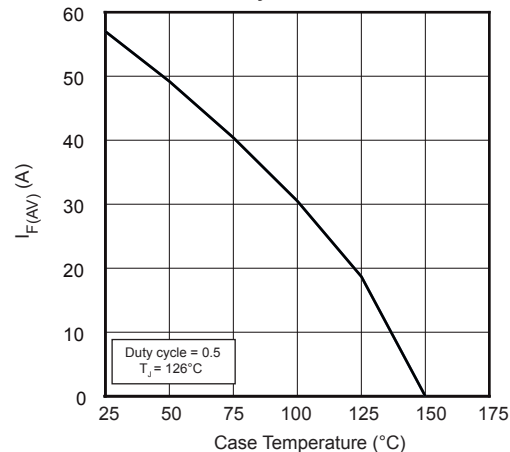


FIGURE 7, Maximum Average Forward Current vs. Case Temperature

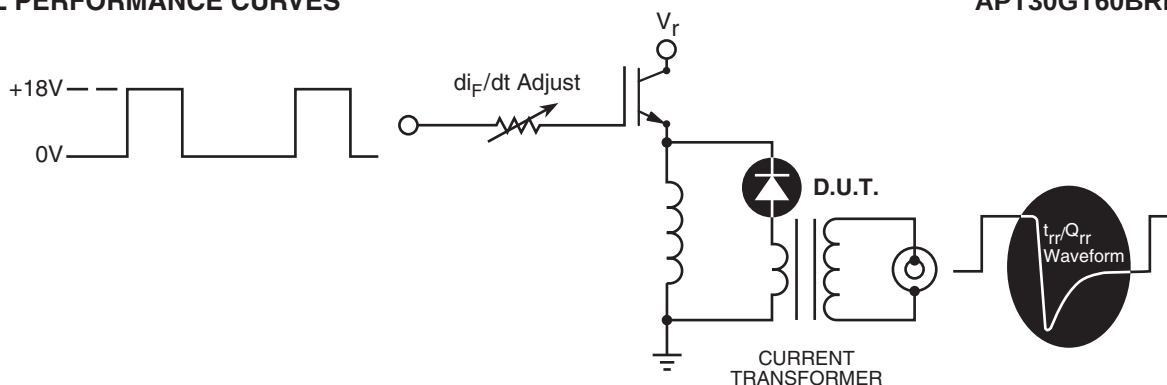


Figure 9. Diode Test Circuit

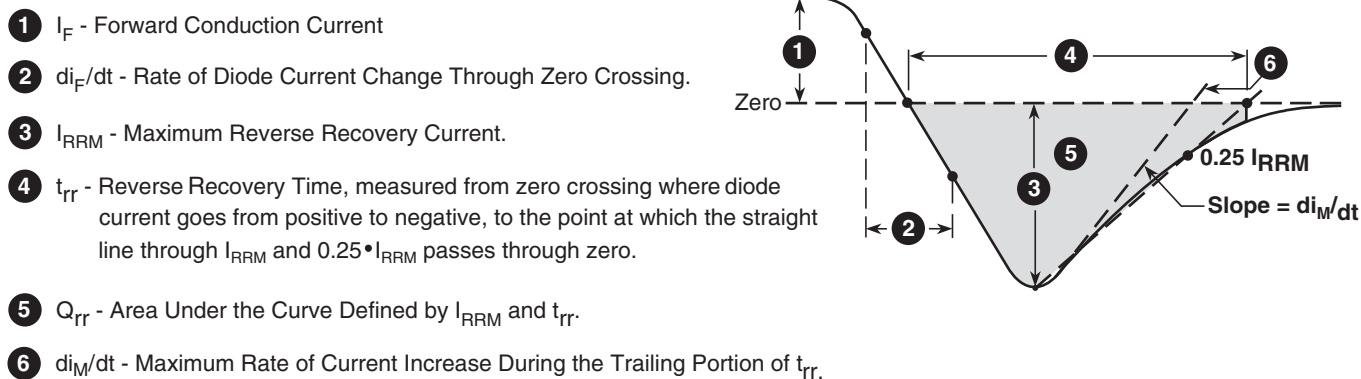
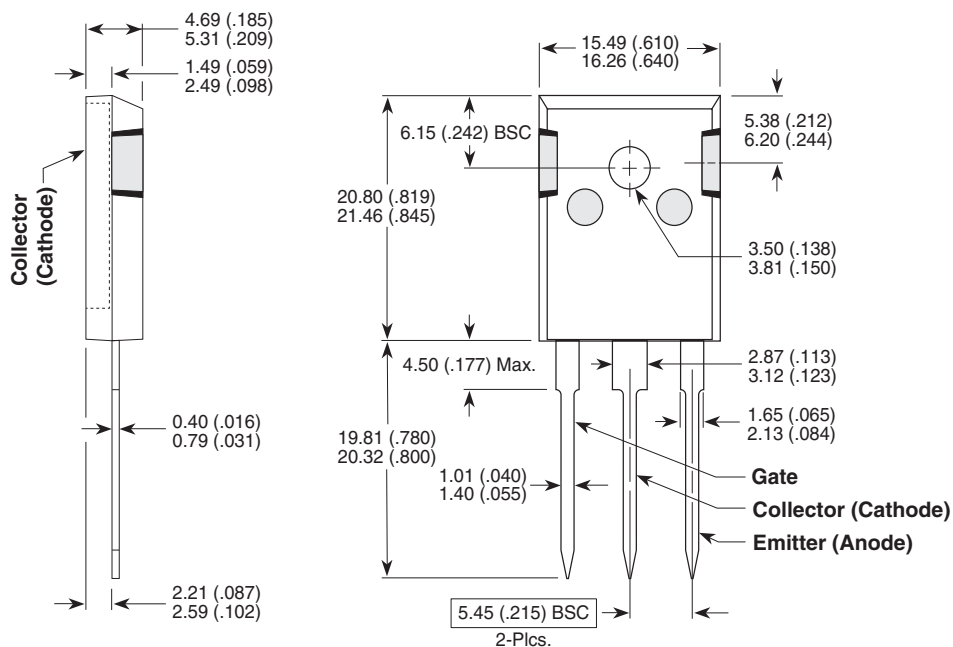


Figure 10. Diode Reverse Recovery Waveform and Definitions

TO-247 (B) Package Outline



Dimensions in Millimeters and (Inches)